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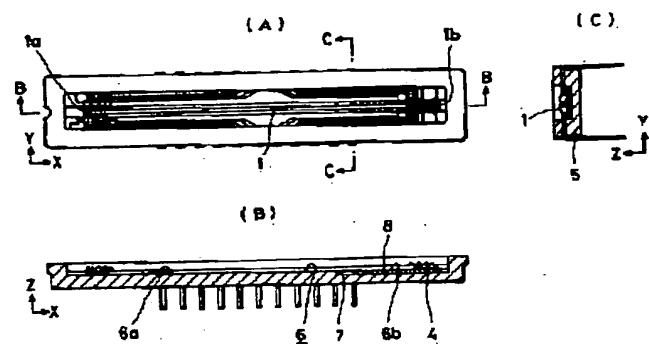
APPLICATION DATE : 01-04-98  
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APPLICANT : SONY CORP;

INVENTOR : UCHIGAWA KUNIHARU;

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TITLE : LINEAR SENSOR AND PACKAGE  
THEREFOR



**ABSTRACT :** PROBLEM TO BE SOLVED: To prevent the generation of the bending or breaking of a solid image pickup element chip or the peeling of adhesive on a boundary face with a package for housing the solid image pickup element chip or the solid image pickup element chip, by removing or reducing any thermal stress due to a linear expansion coefficient difference between the slim solid image pickup element chip and the package.

**SOLUTION:** This linear sensor is formed so that the die attach part of a package 5 for a linear sensor can be constituted of a fixed part 6a and a movable part 8 formed so as to be slidable to the longitudinal direction of the package for the linear sensor, and that a solid image pickup element chip 1 can be adhered to the fixed part 6a of the die attach part and the movable part 8.

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